



## Material Composition

**Product** GS2970-IBE3  
**Package** 100L LBGA  
**Manufacturer** Gennum Corporation

**Date** 15/09/2008

Component	BOM	Weight of Component mg	Substance	Weight of Substance mg	Homogeneous material	
					%	ppm
Substrate	BT	159.840	SiO2	17.023	10.65	106500
			Acrylic	15.984	10.00	100000
			Epoxy	12.787	8.00	80000
			Bisphenol	23.976	15.00	150000
			Triazol	27.972	17.50	175000
			Cu	58.821	36.80	368000
			Ni	2.398	1.50	15000
			Au	0.879	0.55	5500
			Sub-total	159.840	100.00	1000000
Mold Compound	KE-G1250	159.240	Silica (fused)	140.131	88	880000
			Epoxy resin	9.554	6	60000
			Phenolic resin	8.758	5.5	55000
			Carbon black	0.796	0.5	5000
				Sub-total	159.240	100.00
Chip		12.540	Si	12.377	98.7	987000
			Al	0.075	0.6	6000
			W	0.050	0.4	4000
			Ti	0.038	0.3	3000
				Sub-total	12.540	100.00
Die Attach	Ablestik 2100A	6.874	Ag	5.293	77	770000
			Epoxy Resin	0.447	6.5	65000
			Functionalized Resin	0.447	6.5	65000
			Diester	0.687	10	100000
				Sub-total	6.874	100.00
Wire	25_NL03F	3.658	Au	3.658	99.99	999900
Solder Balls	Senju	48.640	Sn	46.938	96.5	965000
			Ag	1.459	3	30000
			Cu	0.243	0.5	5000
				Sub-total	48.640	100.00
<b>Total</b>		390.792				

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